

9/8/04

	L #	Hits	Search Text	DBs
1	L1	92776	(silicon or si or wafer).ti,ab.	USPA T; US-PG PUB
2	L2	10380 1	mold\$4.ti,ab.	USPA T; US-PG PUB
3	L3	1519	1 and 2	USPA T; US-PG PUB
4	L4	39538	etch\$4.ti,ab.	USPA T; US-PG PUB
5	L5	75	3 and 4	USPA T; US-PG PUB
6	L6	10432	(electroplat\$4 or electrodeposit\$8 or electroform\$4 or (electro or electrolytic\$6) adj3 (plat\$4 or deposit\$6 or form\$4)).ti,ab.	USPA T; US-PG PUB
7	L8	91	1 and 4 and 6	USPA T; US-PG PUB
8	L9	852	430/320.ccls.	USPA T; US-PG PUB
9	L10	840	216/2.ccls.	USPA T; US-PG PUB
10	L11	296	216/39.ccls.	USPA T; US-PG PUB
11	L12	37	10 and (2 or 6)	USPA T; US-PG PUB
12	L13	7	3 and (9 or 11)	USPA T; US-PG PUB
13	L14	88	11 and 1	USPA T; US-PG PUB

	L #	Hits	Search Text	DBs
14	L16	21	9 and (1 and 4)	USPA T; US-PG PUB
15	L17	34407	((bottom or second or lower) adj surface).ti,ab.	USPA T; US-PG PUB
16	L19	827	1 with 17	USPA T; US-PG PUB
17	L20	46557 2	(conduct\$6 or metal\$4 or gold or chromium).ti,ab.	USPA T; US-PG PUB
18	L21	4295	((other or opposite) adj surface).ti,ab.	USPA T; US-PG PUB
19	L22	109	1 with 21	USPA T; US-PG PUB
20	L23	90882	20 with (layer or film).ti,ab.	USPA T; US-PG PUB
21	L25	156	(19 or 22) and 23	USPA T; US-PG PUB
22	L26	39	4 and 25	USPA T; US-PG PUB
23	L27	101	(deep adj etch\$4 or deepetch\$4 or dem).ti,ab.	USPA T; US-PG PUB
24	L28	9	1 and 27	USPA T; US-PG PUB
25	L29	21	chen-di.in.	USPA T; US-PG PUB
26	L30	246	205/67.ccls.	USPA T; US-PG PUB

	L #	Hits	Search Text	DBs
27	L31	208	205/70.ccls.	USPA T; US-PG PUB
28	L32	184	205/135.ccls.	USPA T; US-PG PUB
29	L33	12	(30 or 31 or 32) and 1	USPA T; US-PG PUB
30	L34	41	(30 or 31 or 32) and 4	USPA T; US-PG PUB